

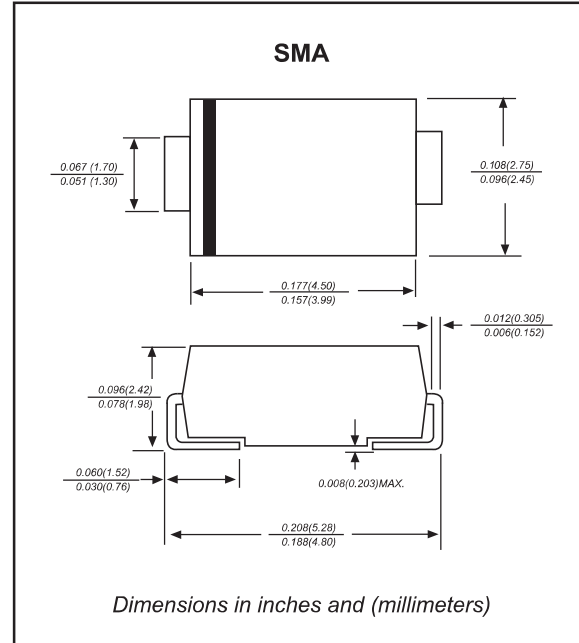
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Fast switching for high efficiency
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds at terminals
- Glass passivated chip junction
- Compliant to RoHS Directive 2011/65/EU

Mechanical data

- **Case:** JEDEC DO-214AC molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

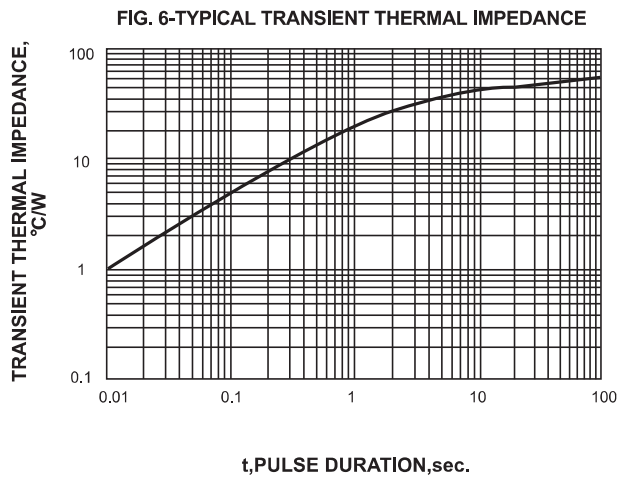
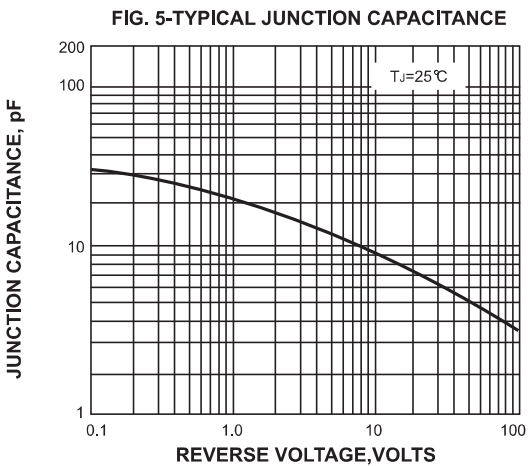
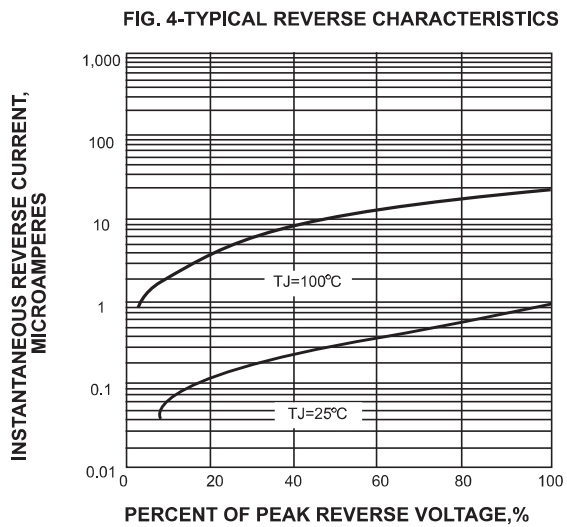
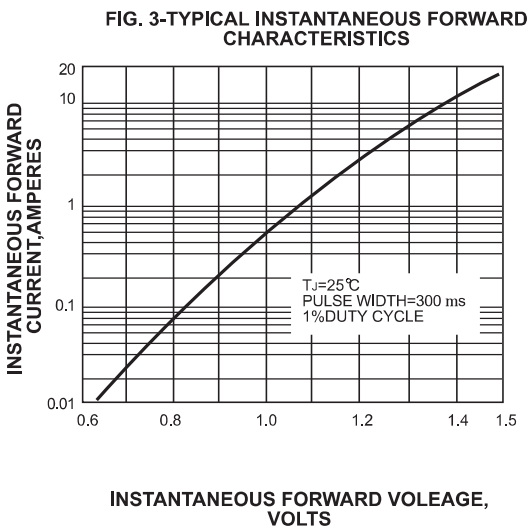
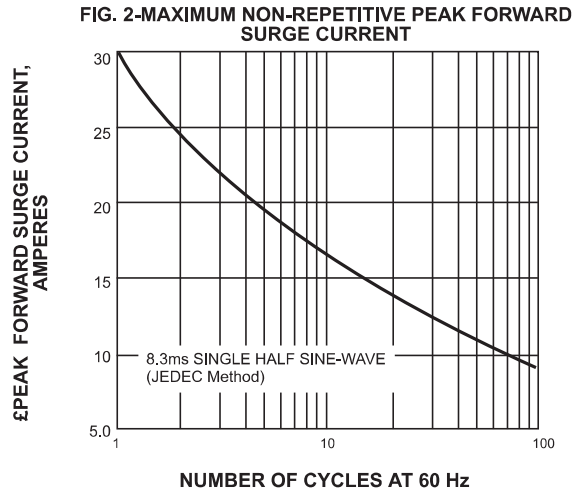
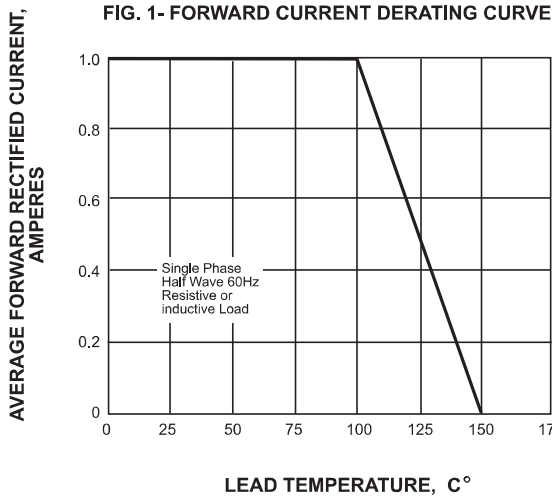
PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I _o			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I _{FSM}			30	A
Reverse current	V _R = V _{RRM} T _A = 25°C	I _R			5.0	μA
	V _R = V _{RRM} T _A = 100°C				50	
Thermal resistance	Junction to ambient NOTE 1	R _{θJA}		75		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C _J		15		pF
Storage temperature		T _{STG}	-55		+150	°C

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	t _{rr} ^{*5} (ns)	Operating temperature T _J , (°C)
RS1A	50	35	50	1.30	150	-55 to +150
RS1B	100	70	100			
RS1D	200	140	200			
RS1G	400	280	400		250	
RS1J	600	420	600			
RS1K	800	560	800		500	
RS1M	1000	700	1000			

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@I_F=1.0A
- *5 Maximum Reverse recovery time, note 2

Note: 1.P.C.B. mounted with 2.0x2.0"(5.0x5.0cm) copper pad areas
2. Reverse recovery time test condition, I_F=0.5A, I_R=1.0A, I_{RR}=0.25A

Rating and characteristic curves



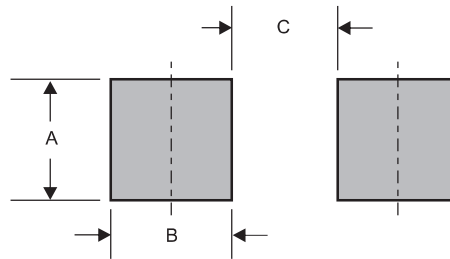
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
RS1A	RS1A	<p>For Halogen Device</p> <p>Marking code</p>
RS1B	RS1B	
RS1D	RS1D	
RS1G	RS1G	
RS1J	RS1J	
RS1K	RS1K	
RS1M	RS1M	

Suggested solder pad layout

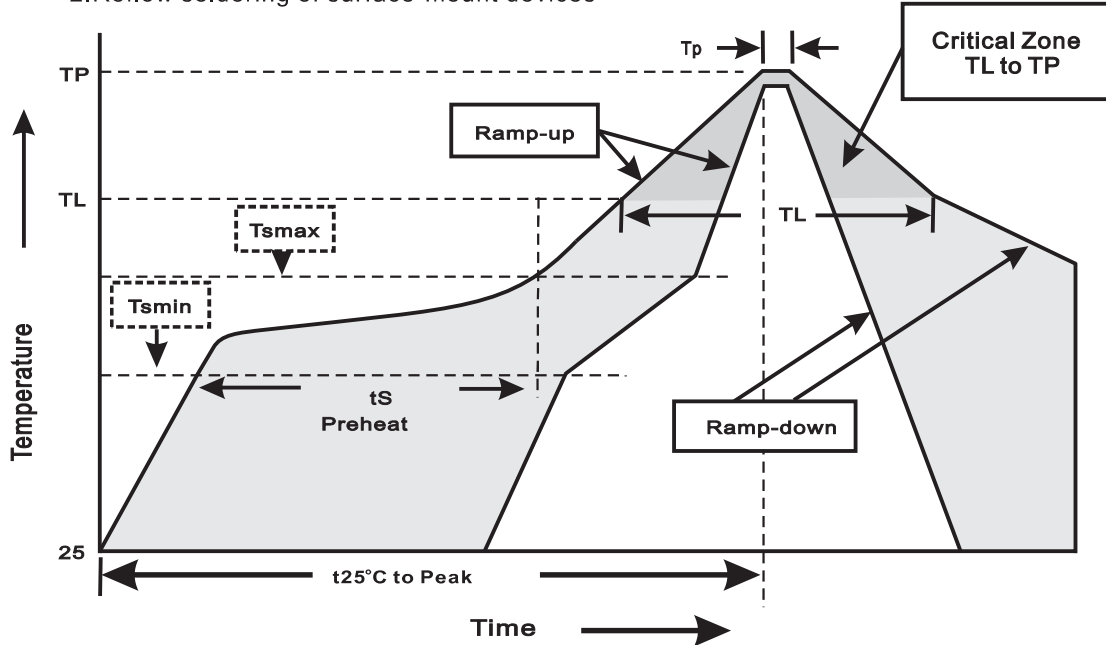


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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